#### 01/31/2017 504205768

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
MASAYUKI IHARA	04/11/2008
KIYOHIKO SUZUKI	04/14/2008
AKINORI KITA	04/14/2008
TADAHIKO KUBOTA	04/14/2008

### **RECEIVING PARTY DATA**

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Street Address:	1-7-1 KONAN, MINATO-KU
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State/Country:	JAPAN

# **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15076135

# CORRESPONDENCE DATA

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THOMAS C. BASSO **Correspondent Name:** Address Line 1: P.O. BOX 1135

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ATTORNEY DOCKET NUMBER:	3712174-03991	
NAME OF SUBMITTER:	THOMAS C. BASSO	
SIGNATURE:	/Thomas C. Basso/	
DATE SIGNED:	01/31/2017	

**Total Attachments: 2** 

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> **PATENT REEL: 041136 FRAME: 0376** 504205768

09792909-7304

	Docket Number:
ASSIGNMENT	
WHEREAS, I, as a below named inventor, residing at the only one name is listed below) or a joint inventor (if plural names are listed ELECTROLYTIC SOLUTION AND BAPTERY	
for which application for Letters Patent of the United States of America was and address;	executed by me on the date indicated next to my name
AND WHEREAS, Sony Corporation, a Japanese corporation, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring a said application disclosing the invention and in, to and under any Letters Patherefor in the United States and in any and all foreign countries;	all interest in, to and under said invention,
NOW THEREFORE, in consideration of the sum of One Do the receipt and sufficience of which are hereby acknowledged, I, as a sole or hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assignterest in the said invention, said application, including any divisions and c Patent of the United States, and countries foreign thereto, which may be grant rights and/or convention rights under the International Convention for the Prote Relating to Patents, Designs and Industrial Models, and any other internation adheres, and to any other benefits accruing or to accrue to me with respect patents in the United States and countries foreign thereto, and I hereby authorized United States Letters Patent to said ASSIGNEE, as the assignee of the vice of the said United States Letters Patent to said ASSIGNEE, as the assignee of the vice of the said ASSIGNEE.	joint inventor as indicated below, b- gns, and legal representatives, the entire right, title and continuations thereof, and in and to any and all Letters ed for said invention, and in and to any and all priority ction of Industrial Property, Inter-American Convention nal agreements to which the United States of America to the filing of applications for patents or securing of ze and request the Commissioner of Patents to issue the
And I further agree to execute all necessary or desirable and lawful ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal and without further remuneration, in order to perfect title in said invention applications and Letters Patent of the United States and countries foreign the	al representatives may from time-to-time present to me, modifications, and improvements in said invention,
And I further agree to properly execute and deliver and without further papers for application for foreign patents, for filing subdivisions of said applications of any Letters Patent which may be granted for my aforesaid invention prepare at its own expense;	lication for patent, and or, for obtaining any reissue or
And I further agree that ASSIGNEE will, upon its request, be proving to said application, said invention and said Letters Patent and legal accessible to me and will testify as to the same in any interference or litigation.	equivalents in foreign countries as may be known and
And I hereby covenant that no assignment, sale, agreement or encum would conflict with this assignment and sale.	brance has been or will be made or entered into which
And I hereby authorize and request my attorney(s) of record in this a this application in the spaces that follow: Serial Number: $\frac{12/123,840}{}$	pplication to insert the serial number and filing date of Filing Date: May 20, 2008
This assignment executed on the dates indicated below.	•
Masayuki IHARA	april 11, 2008
Name of first or sole inventor	Execution date of U.S. Patent Application
Fukushima, Japan	
Residence of first or sole inventor	. ^
Masayuki Shara	April 11, 2008  Date of this assignment
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 020973 FRAME: 0514

PATENT REEL: 041136 FRAME: 0377

Fukushima, Japan Residence of second inventor	ution date of U.S. Patent Application  Wil 14, 208  Date of this assignment  Lpil 14, 208  Ution date of U.S. Patent Application
Fukushima, Japan Residence of second inventor	pril 14, 2008  April 14, 2008
Residence of second inventor  (	Spil 14, 2008
Signature of second inventor	Spil 14, 2008
Signature of second inventor	Spil 14, 2008
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	ition date of U.S. Patent Application
Akinori KITA Qualifornia Executaria Executar	ution date of 0.5. Patent Application
Fukushima,Japan 少村事中心	
desidence of third inventor	design and
Akinoù Kito	pril 14, 2008  Date of this assignment
ignature of third inventor	Date of this assignment
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Tadahiko KUBOTA	April 14, 2018
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Kanagawa, Japan 蒋田横州	
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Tadahiha Kubota	noil/6, 2008
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RECORDED: 05/20/2008

PATENT REEL: 020973 FRAME: 0515

PATENT REEL: 041136 FRAME: 0378

**RECORDED: 01/31/2017**